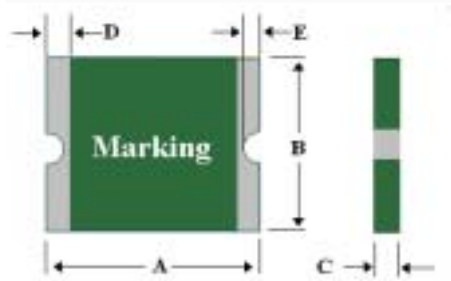
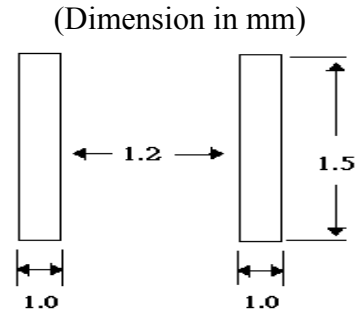


FIGURE

SOLDER PAD LAYOUTS

PHYSICAL DIMENSIONS (mm)

Part Number	A		B		C		D		E
	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Min.	Max.
SMD0805P010TS	2.00	2.20	1.20	1.50	0.55	1.00	0.10	0.20	0.45
SMD0805P020TS	2.00	2.20	1.20	1.50	0.55	1.00	0.10	0.20	0.45
SMD0805P035TS	2.00	2.20	1.20	1.50	0.45	0.75	0.10	0.20	0.45
SMD0805P050TS	2.00	2.20	1.20	1.50	0.75	1.25	0.10	0.20	0.45

All products may be followed by suffix TF

ENVIRONMENTAL SPECIFICATIONS

Operating/Storage Temperature	-40°C to +85°C	
Maximum Device Surface Temperature in Tripped State	125°C	
Passive Aging	+85°C, 1000 hours	±5% typical resistance change
Humidity Aging	+85°C, 85%R.H. 1000 hours	±5% typical resistance change
Thermal Shock	MIL-STD-202 Method 107G +85°C/-40°C 20 times	-30% typical resistance change
Solvent Resistance	MIL-STD-202, Method 215	No change
Vibration	MIL-STD-883C, Method 2007.1, Condition A	No change

PHYSICAL SPECIFICATIONS

Terminal Material	Gold-Plated Copper or Solder-Plated Copper (Solder Material: 63/37 SnPb or Tin(Sn))
Lead Solderability	Meets EIA Specification RS186-9E, ANSI/J-STD-002 Category 3.
Packaging	8 mm tape on 7 inch reel per EIA-481-1 (equivalent to IEC286, part 3) 3000 devices per reel for P050TS, others : 4000 devices per reel

© Specifications are subject to change without notice.

03/28/2003
